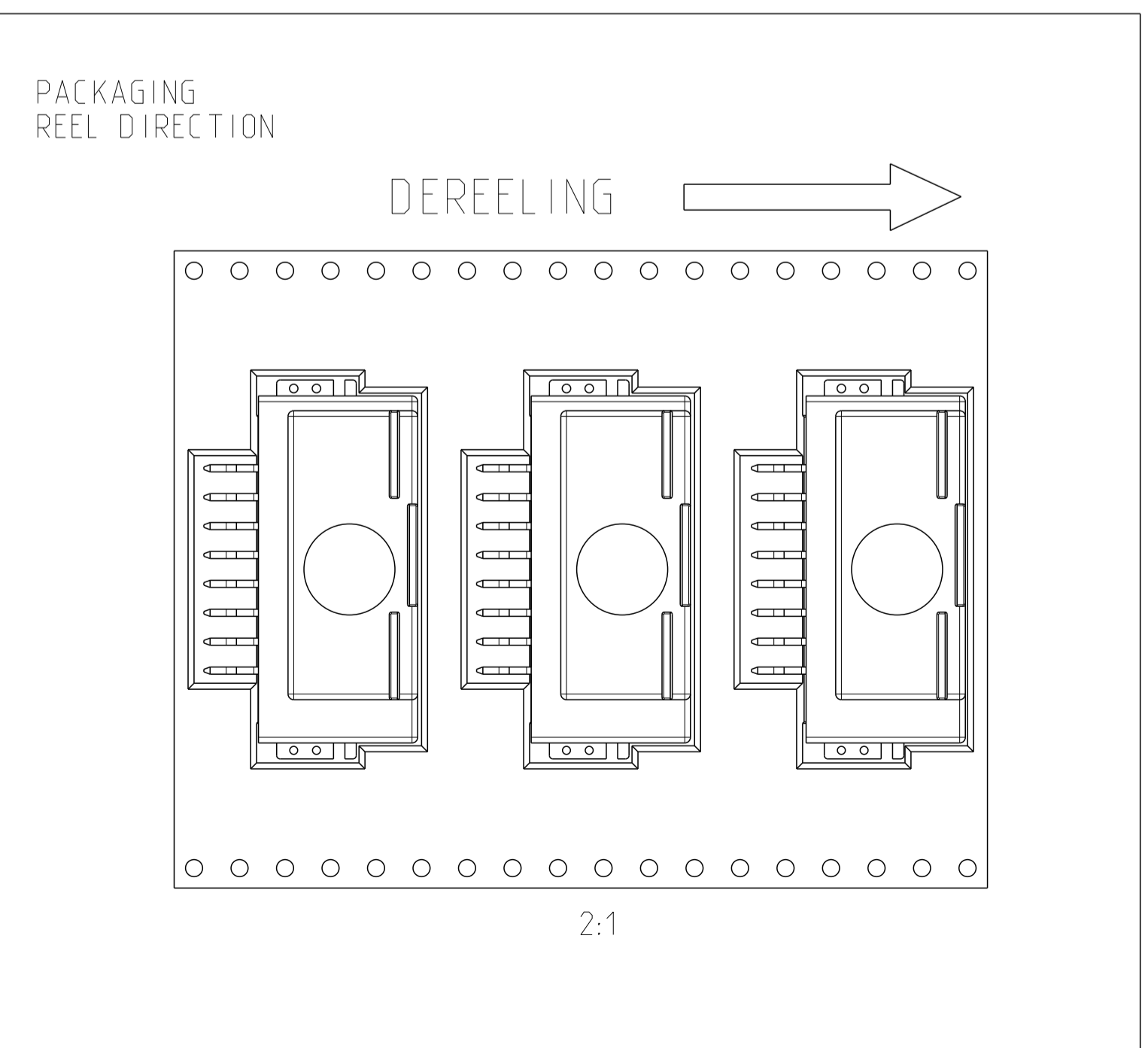
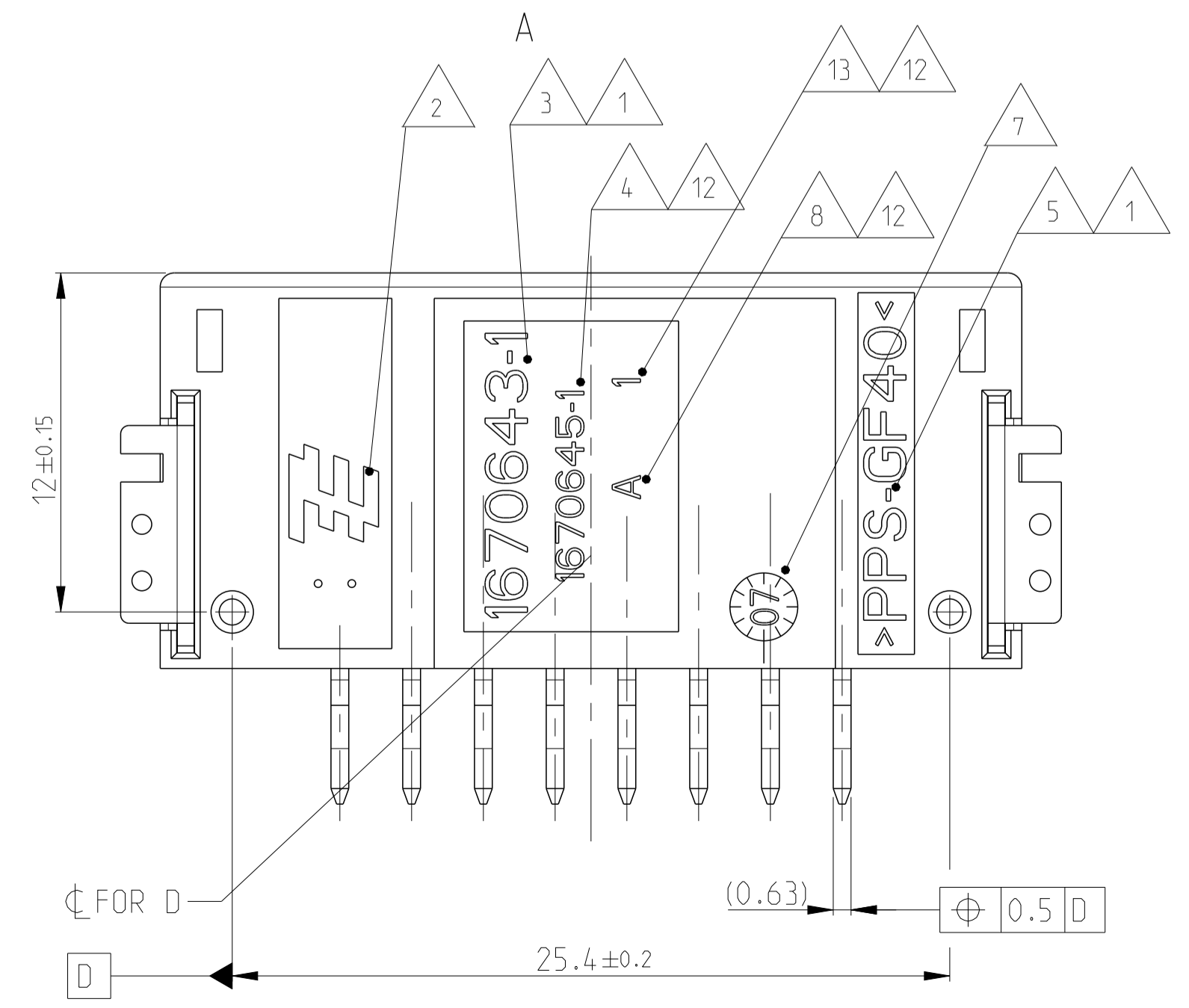
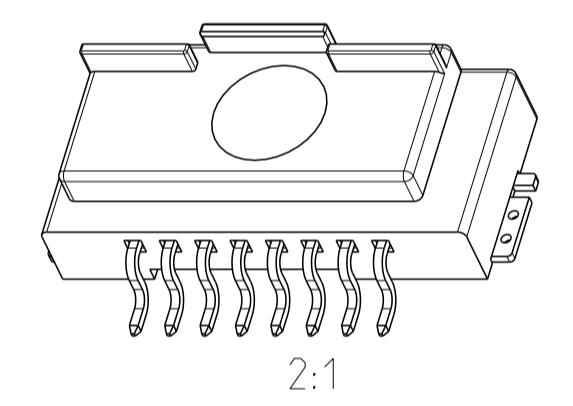
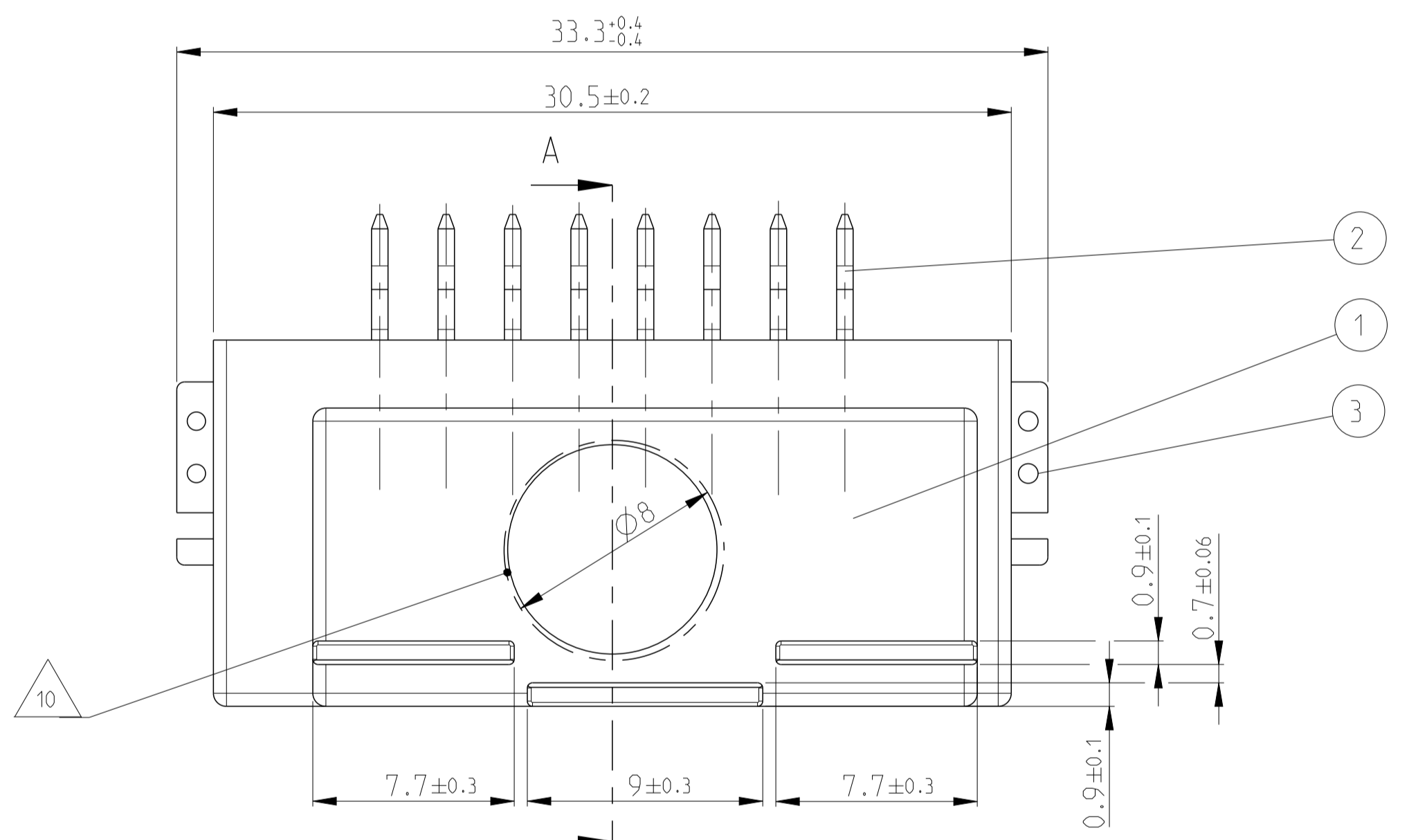
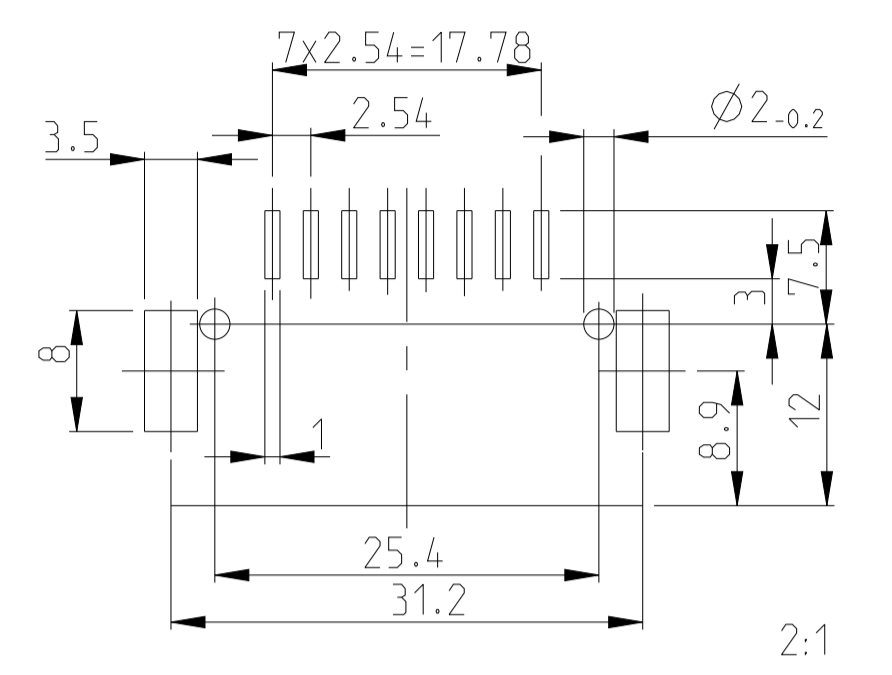


EMPFOLHENES LEITERPLATTEN LAYOUT
RECOMMENDED PCB LAYOUT



NOTES
Bemerkungen

- 1 CHARACTERS 1.5 mm ACCORDING DIN1451. 0.08 mm RAISED IN AN AREA 0.1 mm SUNK
Schrifthöhe 1.5 mm nach DIN 1451; 0.08 mm erhaben im Feld 0.1 mm vertieft
- 2 TE-LOGO
TE-Logo
- 3 TE-ASSY - NO.: EXCHANGEABLE AS A BLOCK
TE-Assy-Nr. auswechselbar als Block
- 4 TE-NO.: EXCHANGEABLE AS A BLOCK
TE- PN. auswechselbar als Block
- 5 MATERIAL IDENTIFICATION
Materialkennzeichnung
- 6 CAVITY IDENTIFICATION
Kammerbezeichnung
- 7 DATE INSERT MONTH/YEAR Ø3mm
Datumstempel Monat/Jahr Ø3mm
- 8 REVISION ACCORDING TO PART-REV. SEPARATELY EXCHANGEABLE
Änderungsindex gemäss Teile-Rev. separat auswechselbar
- 9 MATING CONNECTOR PN1-1394921-1, CODE A
Gegenstecker PN 1-1394921-1, Kodierung A
- 10 VACUUM GRIPPER AREA, FREE OF BURR AND EJECTORS
Ansaugtaeche, frei von Grat und Auswerfern
- 11 CHARACTERS 1 mm ACCORDING DIN1451. 0.1 mm SUNK
Schrifthöhe 1 mm nach DIN 1451; 0.1 mm vertieft
- 12 CHARACTERS 1 mm ACCORDING DIN1451. 0.08 mm RAISED IN AN AREA 0.1 mm SUNK
Schrifthöhe 1 mm nach DIN 1451; 0.08 mm erhaben im Feld 0.1 mm vertieft
- 13 CAVITY NO.
Nestmarkierung
- 14 ACCORDING TO TE MEASURING METHOD 129-18001
Nach TE Meßmethode 129-18001
- 15 PACKAGING INSTRUCTION: V1670643
Verpackungsanweisung: V1670643

1670643-1 AS SHOWN
wie gezeichnet

1670643-2	1	PS	GREY	BLISTER PACKAGING	4
	2	CuZn	4-10 µm Sn	SOLDER BRACKET	3
	8	CuMg0.1	1-4 µm Sn	CONTACT	2
	1	PPS-GF40	BLACK	HOUSING	1
ORDER PART NUMBER QTY.		MATERIAL	SURFACE / COLOR	DESCRIPTION	ITEM
DWN: H. Starke 19MAR2013		CHK: B. Fieberling 19MAR2013	NAME: tyco Electronics	tyco Electronics AMP GmbH 64625 Bensheim (Germany)	
PRODUCT SPEC. / PRODUKTSPEZ.		SMD PIN HEADER MQS 8 POS		RESTRICTED TO NUR FÜR	
APPLICATION SPEC. / VERARBEITUNGSSPEZ.		SMD PIN HEADER MQS 8 POS		-	
MATERIAL		WEIGHT / GEWICHT	SCALE / MASSSTAB	SHEET / BLATT	OF / VON
-		-	5:1	1	1
Customer Drawing		/KUNDENZEICHNUNG		REV A	